

Abstract of the Disclosure

5 The present invention provides an apparatus and method for reducing the likelihood that backspattered material will be deposited on the target while also enhancing target erosion uniformity and efficiency. A target assembly is provided having multiple units or sections separately biased at different bias potentials to provide sputtering of units comprised of target material and preventing backspattered material from depositing on the target units which are minimally sputtered and preferably biased at a lower potential. A method is provided for separately biasing multiple units of a target structure to provide sputtering of units biased at a higher potential and preventing deposition of backspattered material on units biased at a lower potential.

